

Material Profile: Superior™ F880

Superior F880 was specifically developed to be a cost-effective, high-performance compound for semiconductor applications. Superior F880 has the advantage of being compounded with no metallic elements so that it will not yield metal ions as contaminants in high energy plasma applications.

Features and Benefits

- Outstanding plasma resistance
- Minimum particulation
- Wide chemical resistance
- Excellent high temperature compression set resistance
- High physical properties
- Cost-effective

Recommended Processes

- Deposition: CVD, APCVD, HDPCVD, PECVD, RPCVD, SACVD
- Plasma etch: poly, oxide and metal
- Ashing
- Metallization: PVD, sputtering
- Ion Implant
- Chemical vapor deposition
- Lithography

Equipment Locations

- Chamber Lid Seals
- Bell Jar Seals
- Endpoint Windows
- Gas Inlet Seals
- Isolator Valve Seals
- KF Fittings
- Slit Valve Seals
- Valve Seals
- Window Seals



Specialty Fluoroelastomer with No Carbon Fillers

Typical Physical Properties

Color	Ivory
Hardness, Shore A	75
Tensile Strength, psi (MPa)	3205 (22.1)
Elongation	420%
Compression Set: 70 hrs. at 150°C	23%
Service Temperature Range, °C (°F)	-5 to 150 (23 to 302)

NOTE - International Seal, Co. (ISC) is a wholly owned subsidiary of Freudenberg-NOK.

The information contained herein is believed to be reliable, but no representation, guarantees or warranties of any kind are made to its accuracy or suitability for any purpose. The information presented herein is based on laboratory testing and does not necessarily indicate end product performance. Full scale testing and end product performance are the responsibility of the user.

Pub#2504PIC
© Copyright FNGP 2007